

SYSTEM AND METHOD FOR ALIGNING AN INTEGRATED
CIRCUIT DIE ON AN INTEGRATED CIRCUIT SUBSTRATE

ABSTRACT OF THE DISCLOSURE

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10 A system and method is disclosed for aligning an
integrated circuit die on an integrated circuit substrate.
A plurality of deposits of deformable material are placed
on the substrate where the integrated circuit die is to be
aligned. In one advantageous embodiment a stamping tool is
indexed to a first tooling hole and to a second tooling
hole in the substrate. The stamping tool imprints the
deposits of deformable material to a tolerance of less than
one hundred microns with respect to the first and second
tooling holes. The imprinted portions of the deposits to
form a pocket for receiving the integrated circuit die.
This enables the integrated circuit die to be precisely
aligned on the substrate in three dimensions.